

# FABRICATION NOTES

1. FABRICATE PER ANSI/IPC-A-600,IPC-QE-605, IPC-4101,IPC AND IPC-SM-840 SPECIFICATIONS.  
USE OF ROHS-COMPLIANT MATERIALS ENCOURAGED BUT NOT REQUIRED.

2. MATERIAL: BASE MATERIAL LAMINATED EPOXY GLASS FR04, NOM. 0.062" COLOR NATURAL.  
NOM. 1 OZ COPPER WIEGHT. THICKNESS 0.070" MAX AFTER PLATING AND FINISHING.  
PREFER ROHS COMPLIANT PER IPC-4101 SLASH SHEET #26 OR #83 OR #98 WITH  
MINIMUM Tg 135 DEGREE C OR HIGHER, Id 300 DEGREE C OR HIGHER AND FLAME RATED UL94V-0.

3. SOLDERMASK BOTH SIDES OF BOARD OVER BARE COPPER WITH MATERIAL PER ANSI/IPC-SM-840.  
COLOR SHALL BE GREEN.

4. APPLY SOLDER PLATING WITH HOT-AIR LEVELING TP EXPOSED COPPER BOTH SIDES.  
LEAD-FREE SOLDER PREFERRED, LEADED SOLDER ACCEPTABLE.

5. INDICATED AREA ON BOTTOM SIDE AVAILABLE FOR APPICATION OF PCB MANUFACTURED LOGO, UL MARKING, AND DATE-CODE. USE OF OTHER LOCATION TO BE APPROVED BY PURCHASER.

6. APPLY SILKSCREEN TO TOP AND BOTTOM SIDE OF BOARD USING NON-CONDUCTIVE WHITE EPOXY INK.

7. SEE FABRICATION FILE WITH SAME TITLE OR DRAWING NUMBER, AND REVISION, AS THIS DRAWING.

8. DIMENSIONAL TOLERANCES ARE: .XX = +/- .01; .XXX= +/- .005; ANGLE = 2 DEG.

9. OUTLINE DEFINED IN SEPARATE GERBER FILE WITH ".BRD" SUFFIX. DIMENSIONS OF CIRCUMSCRIBED RECTANGLE SHOWN ON THIS DRAWING FOR REF ONLY.

10. SEE SEPARATE DRILL FILE FOR HOLE LOCATIONS.  
SELECTED HOLE LOCATIONS SHOWN ON THIS DRAWING FOR REF ONLY.

11. HOLE LOCATIONS SPECIFIED IN SEPARATE DRILL FILE TAKEN PRECEDENCE OVER THIS DRAWING AND ARTWORK.  
CONTACT PURCHASER TO RESOLVE DIMENSION CONFLICTS BETWEEN DRAWING AND ARTWORK.

12. HOLE SIZES ARE SPECIFIED AS FINAL DIMENSIONS AFTER PLATING AND FINISHING.  
UNLESS OTHERWISE SPECIFIED ALL HOLES TO BE PLATED.

13. VENDOR TO PLATE HOLES AND EXPOSED PADS.  
VENDOR TO SPECIFY TYPE OF PLATING MATERIAL TO BE USED WHEN ACCEPTING ORDER.

14. AFTER ASSEMBLY TRIM SOLDER FILLETS AND COMPONENT LEADS TP 0.06" (MAX)  
BEYOND BOARD SURFACE ON BOTTOM SIDE.

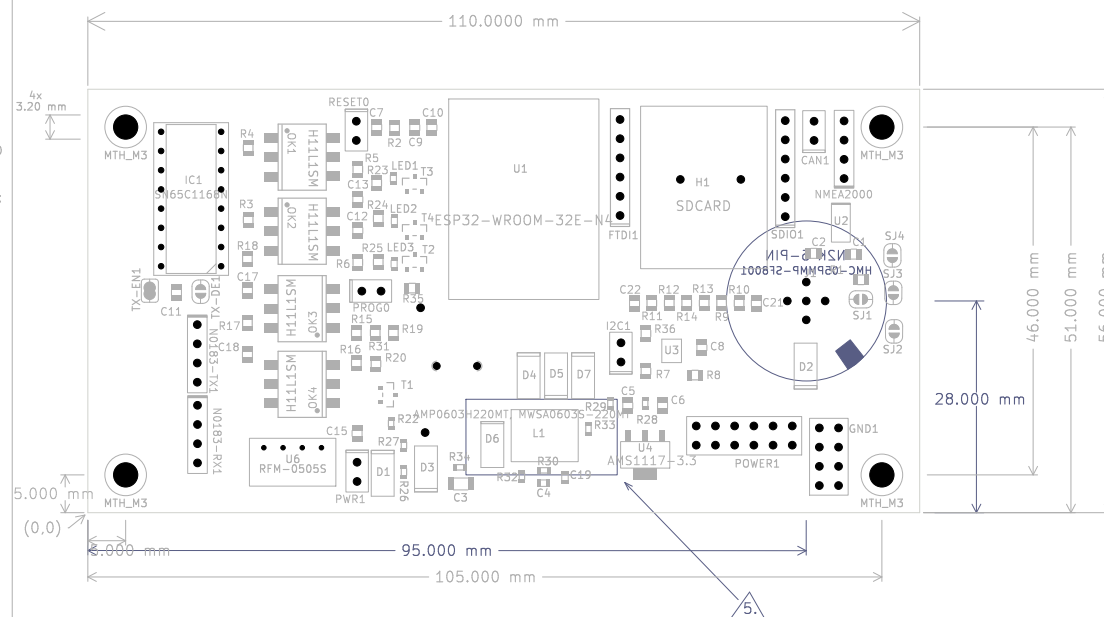
15. DESIGN GEOMETRY MINIMUM FEATURE SIZES:

TRACE WIDTH: ANULUS	6.0 MILS
TRACE-TO-TRACE; TRACE-TO-PAD	6.0 MILS
HOLE-TO-HOLE	9.8 MILS
PAD-TO-PAD	9.8 MILS
SILKSCREEN LINE	6.0 MILS
SILKSCREEN-TO-BARE COPPER	4.0 MILS
MINIMUM HOLE SIZE (PLATED)	11.8 MILS
MAXIMUM HOLE SIZE (UNPLATED)	125 MILS
BOARD EDGE-TO- COPPER	15 MILS

SILKSCREEN (TOP SIDE)	
SOLDER MASK (TOP SIDE)	
TOP LAYER	0.062 IN (1.57mm)
DIELECTRIC	+/- .003 IN (.076mm)
BOTTOM LAYER	THICKNESS OF BOARD
SOLDER MASK (BOTTOM SIDE)	
SILKSCREEN (BOTTOM SIDE)	

TOP - LAYER

BOT - LAYER



## FABRICATION NOTES (BOTTOM):

1. J1 TO BE SEATED ON BACKSIDE OF BOARD TO THE SHOULDER OF THE PINS AND SOLDERED IN PLACE.

The Center for Coastal and Ocean Mapping / NOAA  
UNH Joint Hydrographic Center at the University of New Hampshire

Sheet:

File: WIBL\_V2.5.1\_251121.kicad\_pcb

Title: **Wireless Inexpensive Bathymetry Logger**

Size: A4

Date: 2025-08-20

Rev: **WIBL\_2.5.1**

KiCad E.D.A. 9.0.5

Id: 1/2

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_____	SILKSCREEN (TOP SIDE)	_____
_____	SOLDER MASK (TOP SIDE)	_____
TOP LAYER	_____	0.062 IN (1.57mm) +/- .003 IN (.076mm) THICKNESS OF BOARD
DIELECTRIC	_____	
BOTTOM LAYER	_____	
_____	SOLDER MASK (BOTTOM SIDE)	_____
_____	SILKSCREEN (BOTTOM SIDE)	_____

#### TOP - LAYER

